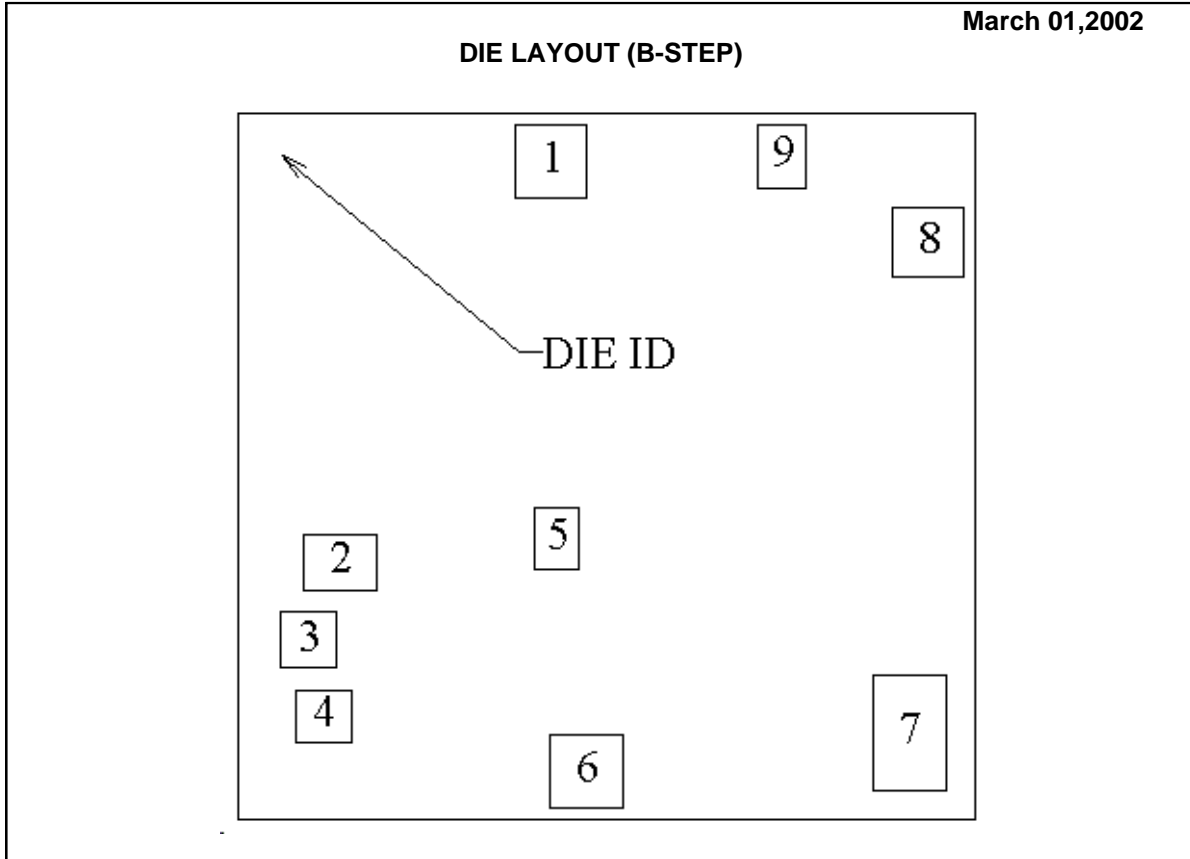


**LM136-5.0 MDS  
VOLTAGE REFERENCE DIODE**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	136B	Bond Pad Opening Size (min)	117 $\mu$ m x 112 $\mu$ m
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	100mm	Back Side Metal	Bare Back
Die Size (Drawn)	1194 $\mu$ m x 1143 $\mu$ m 47mils x 45mils	Back Side Connection	Floating or -
Thickness	330 $\mu$ m Nominal		
Min Pitch	626 $\mu$ m Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection						
SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE		
		X	Y	X	Y	
ADJ	1	-91	495	117	x	117
NC	2	-432	-155	117	x	91
NC	3	-483	-282	91	x	91
NC	4	-460	-406	91	x	86
NC	5	-81	-117	71	x	97
+	6	-33	-495	117	x	117
NC	7	491	-432	119	x	188
-	8	521	363	117	x	112
NC	9	284	502	81	x	104

**LM136-5.0 MDS**  
**VOLTAGE REFERENCE DIODE**

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